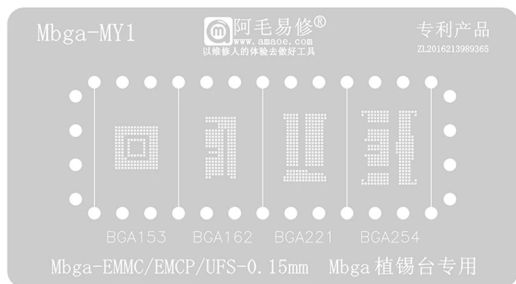


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## AMAOE BGA Mbga-MY1 stencil reballing BGA EMMC/EMCP/UFS BGA153 BGA162 BGA221 BGA254 0,15mm

Product ID: 23031

Price: **7.00 EUR**

Product weight: **0.20 kg**

### Description:

AMAOE BGA Mbga-MY1 stencil reballing BGA EMMC/EMCP/UFS BGA153 BGA162 BGA221 BGA254 0,15mm - the sieves are a product made of steel resistant to high temperatures and deformations. Precise laser-cut templates facilitate positioning during work.

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